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TITLE: 400 I/O, FINE PITCH, PBGA, 17 X 17 PKG, 0.8MM PITCH (STD MAP)	DOCUMENT NO: 98ASA10507D	REV: A	
	CASE NUMBER: UNKNOWN	31 MAY 2005	
	STANDARD: NON-JEDEC		



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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